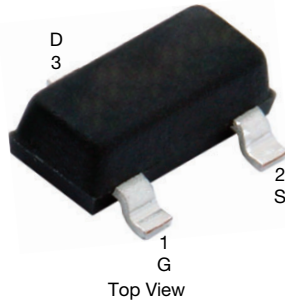


N-Channel 8 V (D-S) MOSFET

SOT-23 (TO-236)



Marking code: F2

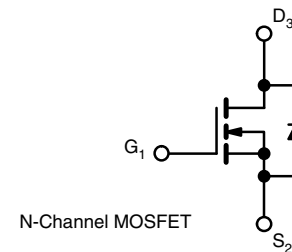
PRODUCT SUMMARY	
V_{DS} (V)	8
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5$ V	0.017
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 2.5$ V	0.020
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 1.8$ V	0.022
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 1.5$ V	0.030
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 1.2$ V	0.075
Q_g typ. (nC)	6
I_D (A) ^{a, e}	6
Configuration	Single

FEATURES

- TrenchFET[®] power MOSFET
- Low on-resistance
- 100 % R_g tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Load switches for low voltage gate drive
- Low voltage operating circuits
 - Gate drive 1.2 V to 5 V


RoHS
 COMPLIANT
 HALOGEN
FREE

ORDERING INFORMATION	
Package	SOT-23
Lead (Pb)-free and halogen-free	Si2342DS-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V_{DS}	8	V
Gate-source voltage		V_{GS}	± 5	
Continuous drain current ($T_J = 150$ °C)	$T_C = 25$ °C	I_D	6 ^e	A
	$T_C = 70$ °C		6 ^e	
	$T_A = 25$ °C		6 ^{b, c, e}	
	$T_A = 70$ °C		5.8 ^{b, c}	
Pulsed drain current ($t = 300$ μ s)		I_{DM}	30	
Continuous source-drain diode current	$T_C = 25$ °C	I_S	2.1	
	$T_A = 25$ °C		1.1 ^{b, c}	
Maximum power dissipation	$T_C = 25$ °C	P_D	2.5	W
	$T_C = 70$ °C		1.6	
	$T_A = 25$ °C		1.3 ^{b, c}	
	$T_A = 70$ °C		0.8 ^{b, c}	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to +150	°C
Soldering recommendations (peak temperature)			260	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^{b, d}	$t \leq 5$ s	R_{thJA}	75	100	°C/W
Maximum junction-to-foot (drain)	Steady state	R_{thJF}	40	50	

Notes

- Based on $T_C = 25$ °C
- Surface mounted on 1" x 1" FR4 board
- $t = 5$ s
- Maximum under steady state conditions is 166 °C/W
- Package limited

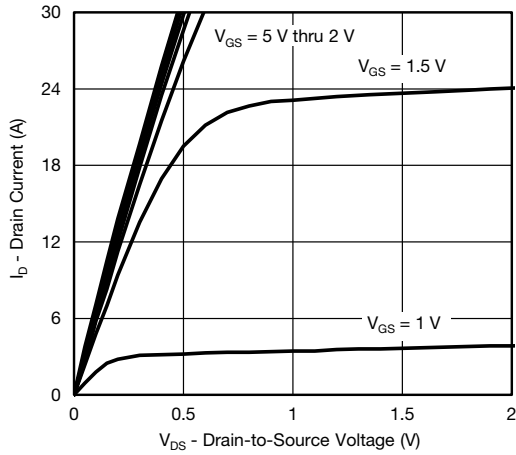
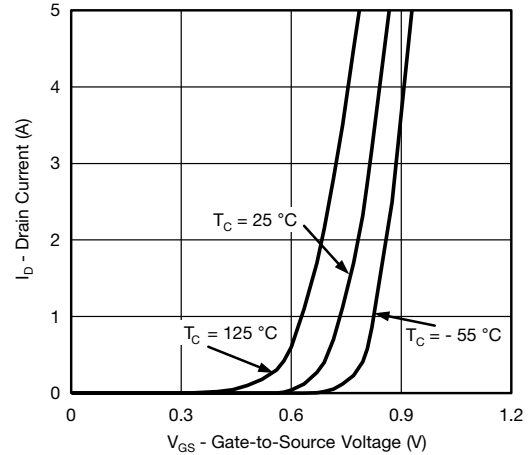
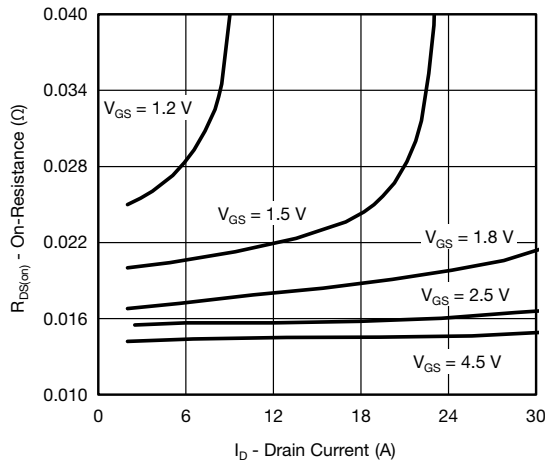
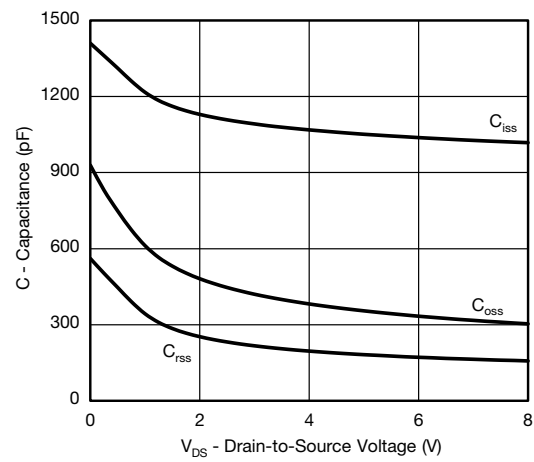
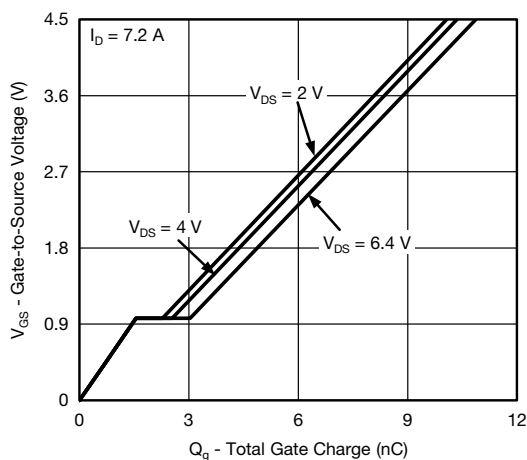
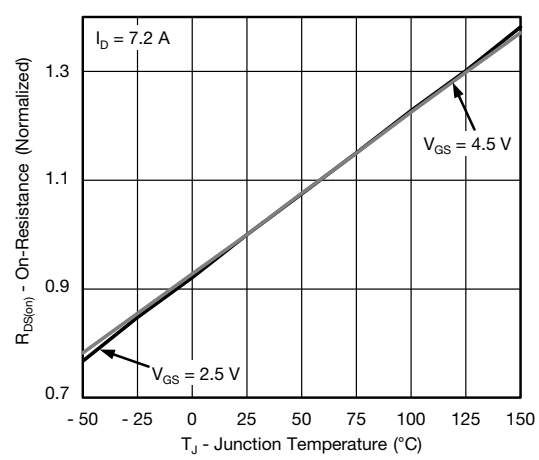


SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	8	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$	-	10	-	mV/ $^\circ\text{C}$
$V_{GS(th)}$ temperature coefficient	$\Delta V_{GS(th)}/T_J$		-	-2.5	-	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	0.35	-	0.8	V
Gate-source leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 5\text{ V}$	-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 8\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	μA
		$V_{DS} = 8\text{ V}, V_{GS} = 0\text{ V}, T_J = 70\text{ }^\circ\text{C}$	-	-	10	
On-state drain current ^a	$I_{D(on)}$	$V_{DS} \leq 5\text{ V}, V_{GS} = 4.5\text{ V}$	20	-	-	A
Drain-source on-state resistance ^a	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}, I_D = 7.2\text{ A}$	-	0.014	0.017	Ω
		$V_{GS} = 2.5\text{ V}, I_D = 6.7\text{ A}$	-	0.016	0.020	
		$V_{GS} = 1.8\text{ V}, I_D = 6.4\text{ A}$	-	0.018	0.022	
		$V_{GS} = 1.5\text{ V}, I_D = 5.5\text{ A}$	-	0.020	0.030	
		$V_{GS} = 1.2\text{ V}, I_D = 1.3\text{ A}$	-	0.025	0.075	
Forward transconductance ^a	g_{fs}	$V_{DS} = 4\text{ V}, I_D = 7.2\text{ A}$	-	75	-	S
Dynamic ^b						
Input capacitance	C_{iss}	$V_{DS} = 4\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	-	1070	-	pF
Output capacitance	C_{oss}		-	385	-	
Reverse transfer capacitance	C_{rss}		-	200	-	
Total gate charge	Q_g	$V_{DS} = 4\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 7.2\text{ A}$	-	10.5	15.8	nC
		$V_{DS} = 4\text{ V}, V_{GS} = 2.5\text{ V}, I_D = 7.2\text{ A}$	-	6	9	
Gate-source charge	Q_{gs}		-	1.6	-	
Gate-drain charge	Q_{gd}		-	1	-	
Gate resistance	R_g	$f = 1\text{ MHz}$	2.4	12	24	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 4\text{ V}, R_L = 0.7\text{ }\Omega,$ $I_D \cong 5.8\text{ A}, V_{GEN} = 4.5\text{ V}, R_g = 1\text{ }\Omega$	-	6	12	ns
Rise time	t_r		-	14	20	
Turn-off delay time	$t_{d(off)}$		-	65	98	
Fall time	t_f		-	25	38	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	$T_C = 25\text{ }^\circ\text{C}$	-	-	2.1	A
Pulse diode forward current	I_{SM}		-	-	30	
Body diode voltage	V_{SD}	$I_S = 5.8\text{ A}, V_{GS} = 0$	-	0.82	1.2	V
Body diode reverse recovery time	t_{rr}	$I_F = 5.8\text{ A}, di/dt = 100\text{ A}/\mu\text{s},$ $T_J = 25\text{ }^\circ\text{C}$	-	40	60	ns
Body diode reverse recovery charge	Q_{rr}		-	17	26	nC
Reverse recovery fall time	t_a		-	15	-	ns
Reverse recovery rise time	t_b		-	25	-	

Notes

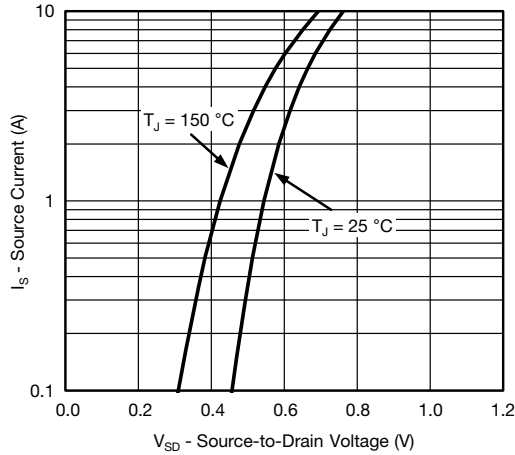
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

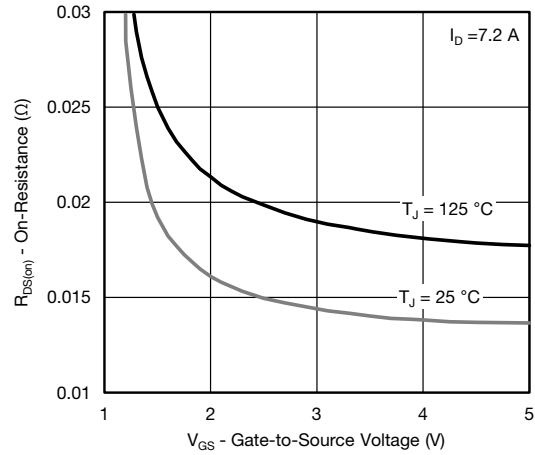
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current and Gate Voltage

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature



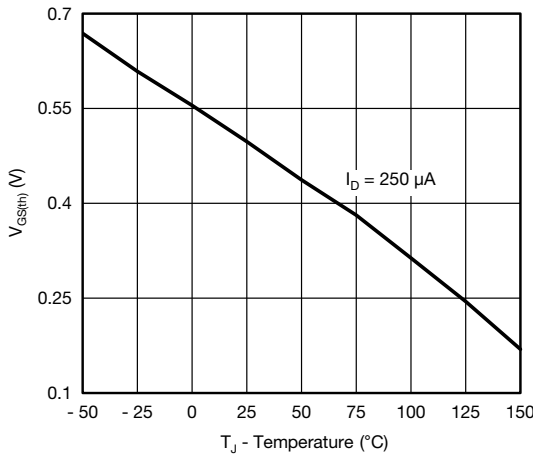
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



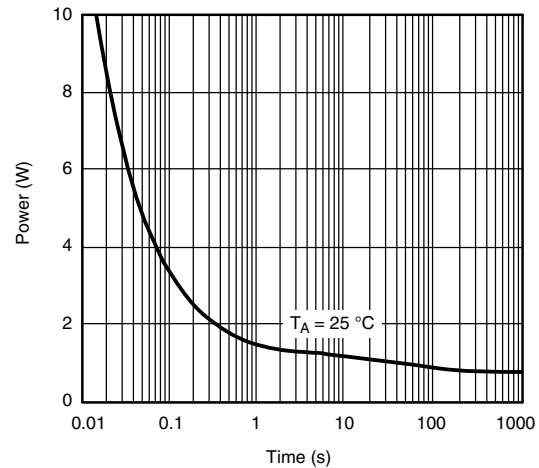
Source-Drain Diode Forward Voltage



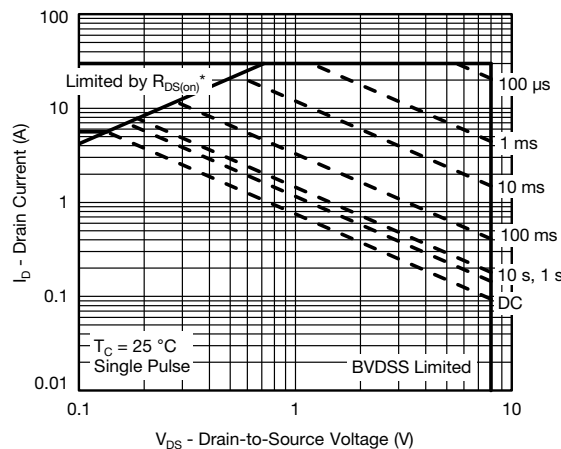
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



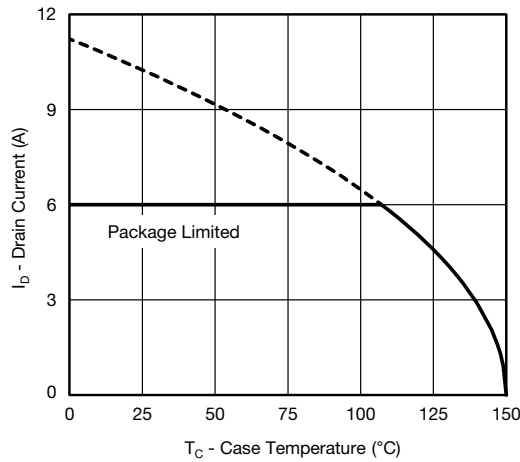
Single Pulse Power (Junction-to-Ambient)



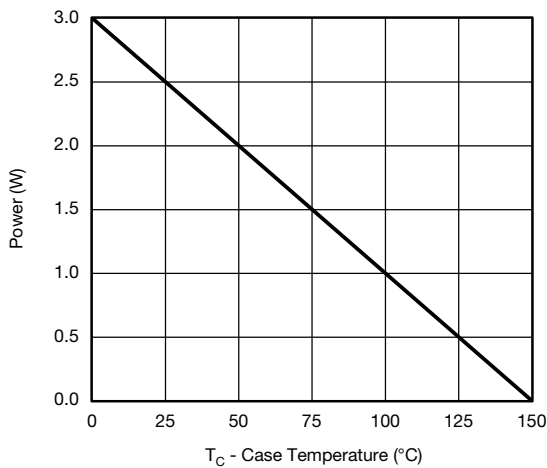
Safe Operating Area, Junction-to-Ambient



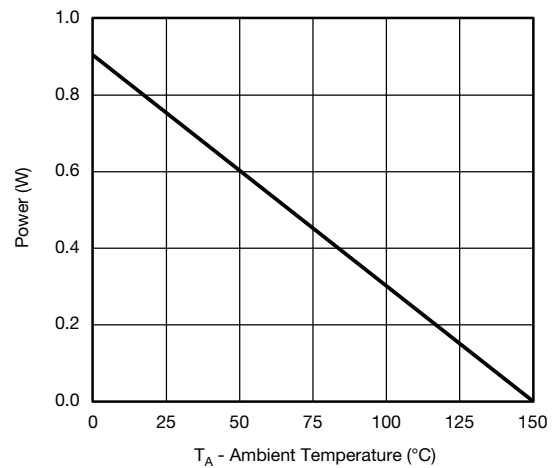
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating^a



Power Derating, Junction-to-Foot



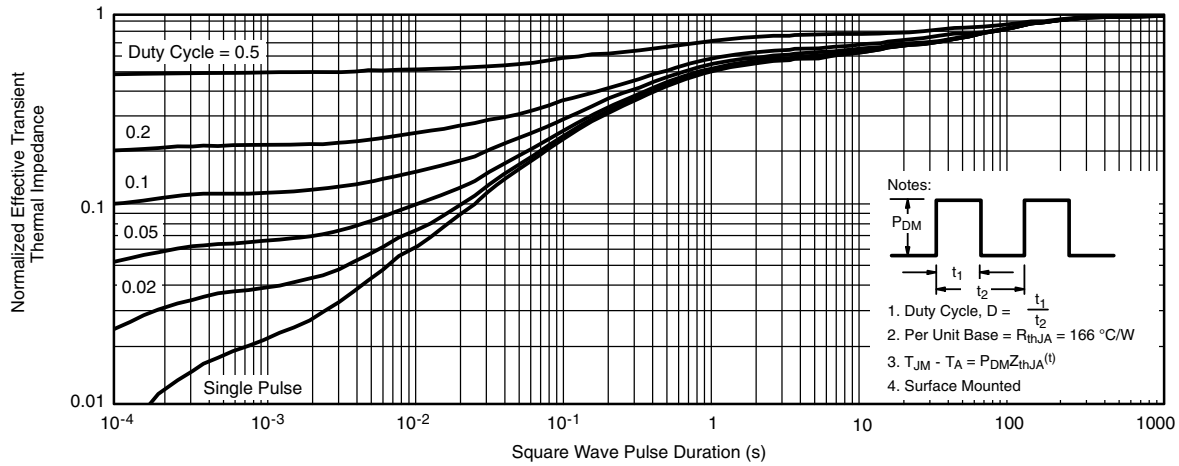
Power Derating, Junction-to-Ambient

Note

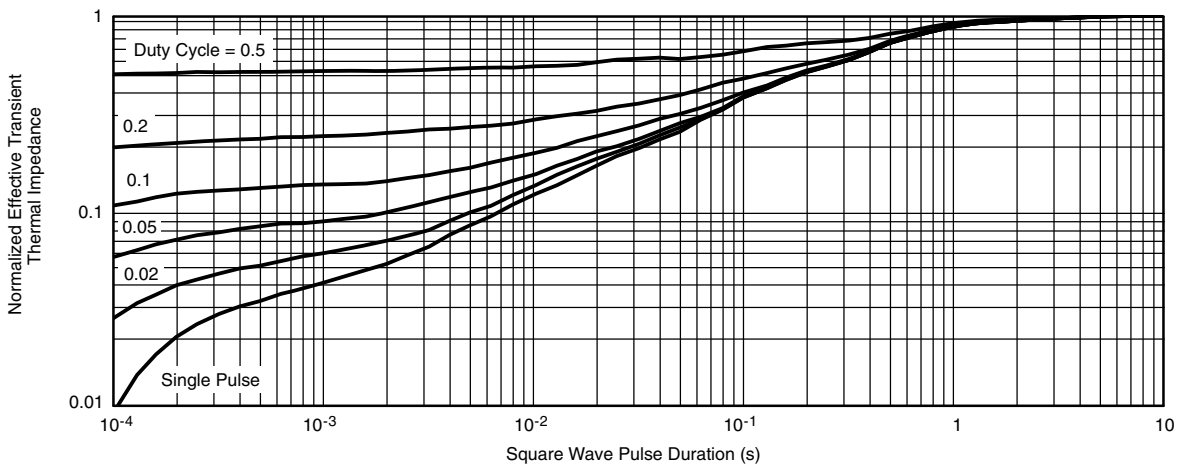
- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOT-23 (TO-236): 3-LEAD



Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	0.89	1.12	0.035	0.044
A ₁	0.01	0.10	0.0004	0.004
A ₂	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
c	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E ₁	1.20	1.40	0.047	0.055
e	0.95 BSC		0.0374 Ref	
e ₁	1.90 BSC		0.0748 Ref	
L	0.40	0.60	0.016	0.024
L ₁	0.64 Ref		0.025 Ref	
S	0.50 Ref		0.020 Ref	
q	3°	8°	3°	8°

ECN: S-03946-Rev. K, 09-Jul-01
 DWG: 5479

RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads
Dimensions in Inches/(mm)

[Return to Index](#)



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